

Beyond Smart Manufacturing



SCM200 M2M Chip Personalization Machine

Focusing on data personalized production for WLCSP chips









SEM200 M2M Chip Personalization Machine



Materials:



Materials after production:



The M2M Chip Personalization Machine SCM200 can conduct chip electrical performance test, chip Perso and surface laser marking for M2M chips in WLCSP packaging forms. Scalable support for personalized processing of chips such as DFN8-5 * 6, DFN8-2 * 2, and VSOP8 and other packaging forms.

SCM200 can provide high-speed, stable and safe personalization production services for global mobile operators, smart device OEMs, and automotive electronic security chip manufacturers. And it can flexibly and quickly switch production orders with different packaging forms.

Key Features & Advantages

High Stability:

- ▶ Rejecting rate is less than 1/1000.
- ▶ Focusing on data personalized production for WLCSP chips.
- ▶ High-precision of mechanical carrying mechanism can handle chips down to 1.4*1.8mm.

High Cost-performance Ratio:

► The customer procurement costs can be reduced by 15% due to variety of self-developed core technologies integrated.

► The maintenance costs can be reduced by 20% with less wearing and longer service life.

High Compatibility:

Dozens of chips in different froms and specifications can be

supported, and switching time is less than 20 minutes.

- Support Tape input.
- Secondary development is fully supported to meet various customized requirements.

High Flexibility:

Small footprint and flexible configuration.

Configurations



Input/output Module:

•Tape Input: Compatible with tape rolls in 1000pcs (the tape disc's diameter: 180mm) and 3000pcs (the tape disc's diameter: 330mm) . •Tape Input: tape in 8mm is supported,

12mm, 16mm and 24mm is extensible;



Laser Marking Module: •Equipped with 1 set of 20W fiber laser. •Equipped with 1 set of extractor.



Chip Positioning Module:

•Equipped with 2 chip storage stations. *Positioning the chip to ensure accurate positioning, and can rotate the chip by 90°, -90°, and 180° *One placed at the rear of tape input module and one placed at the front of tape output module, for adjusting the direction of chips when entering the IC Perso module and output module.



OCR Verification Module:

•Equipped with a set of 5 million pixel industrial camera (including light source).

•Equipped with a set of OCR software. *Surface information of chips can be recognized and verified.



IC perso Module:

•Standard: 4 perso stations, Extensible: 8 perso stations

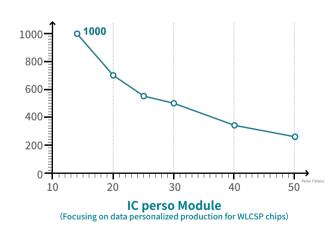
•Standard: 1 pcs of PIOTEC 4IN1 contact readers.Extensible: 2 pcs of PIOTEC 4IN1 contact readers.

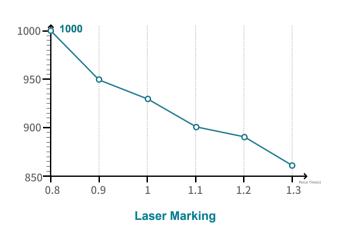
*Support Chip Perso and remaking online function. Supporte ISO7816, Serial port, Bluetooth, SPI and I2C protocols. *Support IC data verification function.

Reject Module:

• Equipped with 1 reject boxes. *Chips which fail to be Perso or marked can be rejected automatically and stored in different categories to reduce material loss and labor costs.

Throughput





Technical Specification

Dimension:	1250mm×950mm×1870mm	
	(Excluding the tape bracket section)	
Weight:	450Kg	
Power Supply:	220V(-5%~+10%), 50Hz, 3KW	
Noise:	≤65dB	

Operation Temperature:	23°C±3°C
Operation Humidity:	50±10%rh
Compressed Air:	Pressure:0.5Mpa Flow:300LPM
Communication Interface:	Ethernet

Partners



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